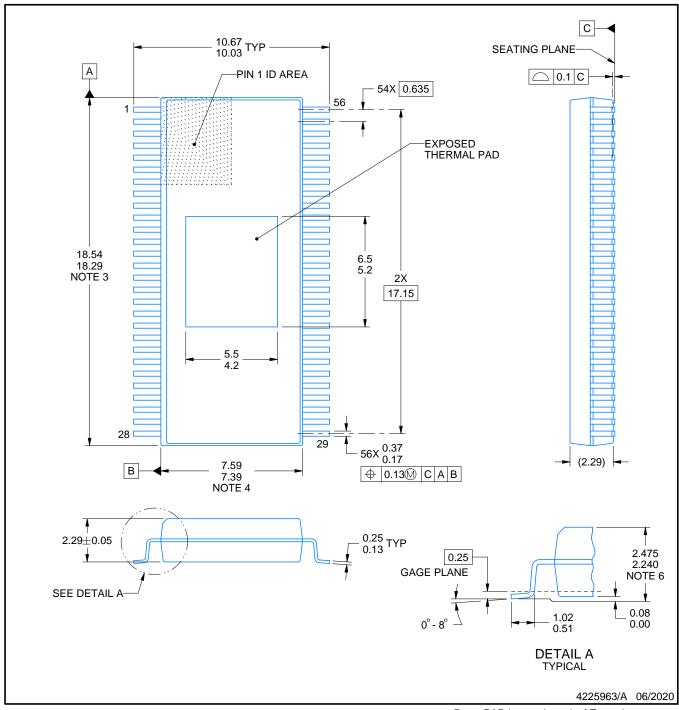


PLASTIC SMALL OUTLINE



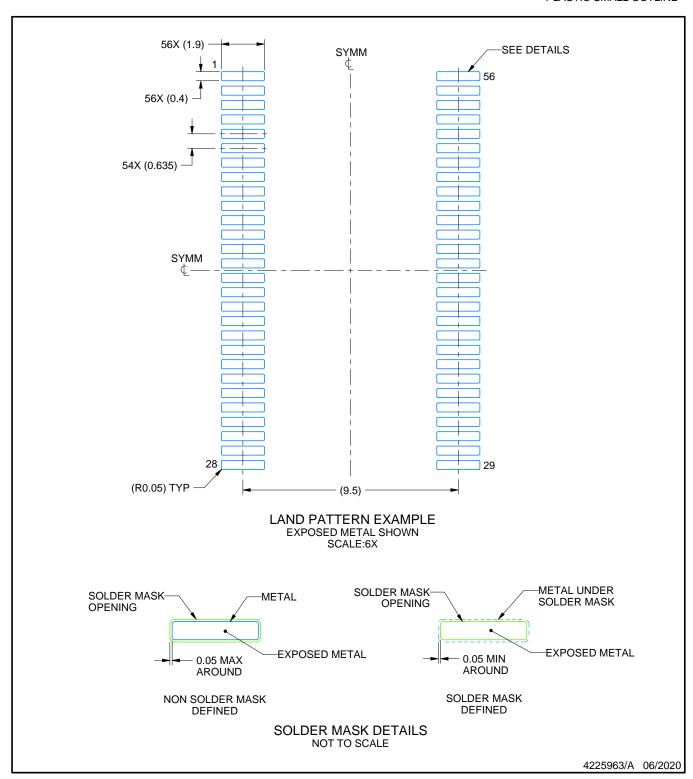
NOTES:

PowerPAD is a trademark of Texas Instruments.

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. The exposed thermal pad is designed to be attached to an external heatsink.
- 6. For clamped heatsink design, refer to overall package height above the seating plane as 2.325 +/- 0.075 and molded body thickness dimension.



PLASTIC SMALL OUTLINE

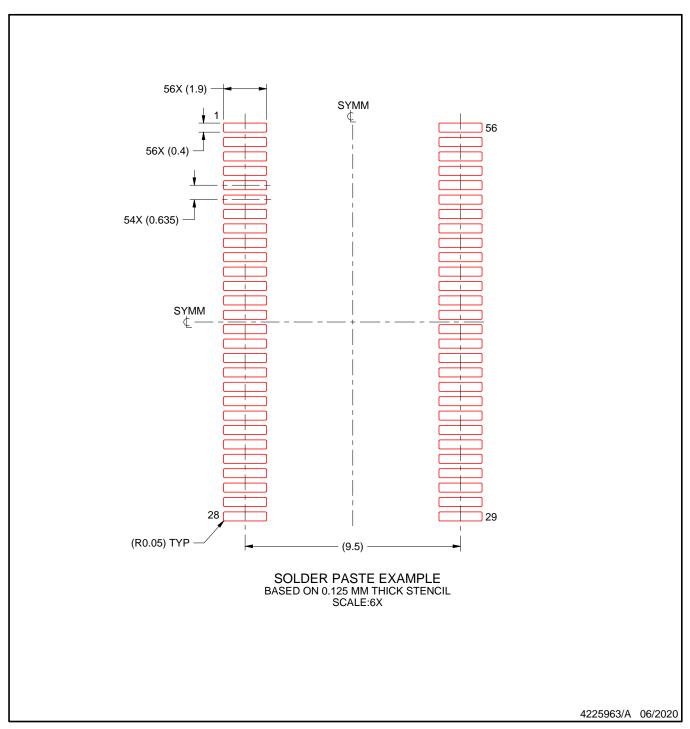


NOTES: (continued)

- 7. Publication IPC-7351 may have alternate designs.
- 8. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
- 9. Size of metal pad may vary due to creepage requirement.



PLASTIC SMALL OUTLINE



NOTES: (continued)



^{10.} Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

^{11.} Board assembly site may have different recommendations for stencil design.